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Name: Commissioner of Patents

Art Unit: 2826

Examiner: Fetsum Abraham

Phone: (703) 305-3793

From: Daniel R. Kimball
Reg No. 34,849

Re: Application No. 09/383,150
Filed August 25, 1999

Entitled **LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE INCORPORATING
MULTIPLE INTEGRATED CIRCUIT CHIPS, AND METHOD OF
FABRICATING A SEMICONDUCTOR CHIP...**

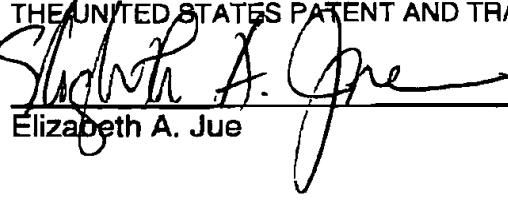
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I HEREBY CERTIFY THAT THIS PAPER IS BEING FACSIMILE TRANSMITTED TO
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Elizabeth A. Jue

*Correspondence: Amendment Transmittal; Amendment After Final

For Office Services Use Only
Return to Elizabeth A. Jue

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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
AMENDMENT TRANSMITTAL LETTER

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at (703) 308-7722 on June 23, 2003.

Elizabeth A. Yue

Applicant : Rong-Fuh Shyu
Application No. : 09/383,150
Filed : August 25, 1999
Title : LEAD FRAME FOR A SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE INCORPORATING MULTIPLE
INTEGRATED CIRCUIT CHIPS, AND METHOD OF FABRICATING
A SEMICONDUCTOR CHIP PACKAGE WITH MULTIPLE
INTEGRATED CIRCUIT CHIPS
Grp./Div. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

JUN 23 2003

PostOffice Box 7068
Pasadena, CA 91109-7068
June 23, 2003

Commissioner:

TECHNOLOGY CENTER 2800

Enclosed is an amendment to the above-identified application.

CLAIMS AS AMENDED						
	Claims Remaining After Amendment	Highest Number Paid For	Number Extra Claims	Small Entity Rate	Large Entity Rate	FEE
Total Claims Fee	4	*20		x \$9.00	x \$18.00	
Independent Claims	1	** 3		x \$42.00	x \$84.00	
Multiple Dependent Claims ***				\$140.00	\$280.00	
TOTAL FILING FEE						0
NO ADDITIONAL FEE REQUIRED ****						0

**Amendment Transmittal Letter
Application No. 09/383,150**

Attached is our check for \$ to pay the fees calculated above.
A Petition for Extension of Time and the required fee are enclosed.
Other enclosures:

The Commissioner is hereby authorized to charge any fees under 37 CFR 1.16 and 1.17 which may be required by or to give effect to this paper to Deposit Account No. 03-1728. Please show our docket number with any charge or credit to our Deposit Account. A copy of this letter is enclosed.

Respectfully submitted,

CHRISTIE, PARKER & HALE, LLP

By 
~~Daniel R. Kimball~~
Reg. No. 34,849
626/795-9900

DRK/eaj

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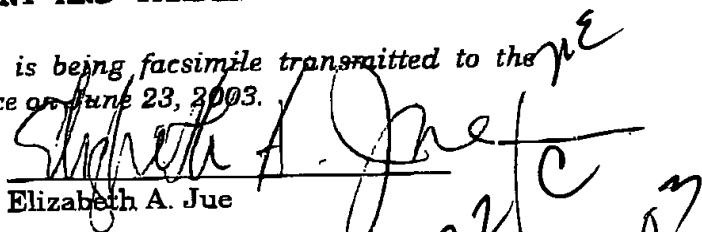
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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2826

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Elizabeth A. Jue

Appln No. : 09/383,150
Applicant : Rong-Fuh Shyu
Filed : August 25, 1999
Title : LEAD FRAME FOR A
SEMICONDUCTOR CHIP PACKAGE,
SEMICONDUCTOR CHIP PACKAGE
INCORPORATING MULTIPLE
INTEGRATED CIRCUIT CHIPS, AND
METHOD OF FABRICATING A
SEMICONDUCTOR CHIP PACKAGE
WITH MULTIPLE INTEGRATED
CIRCUIT CHIPS
TC/A.U. : 2826
Examiner : Fetsum Abraham
Docket No. : 35761/DBP/S295

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MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Post Office Box 7068
Pasadena, CA 91109-7068
June 23, 2003

Sir:

AMENDMENT AFTER FINAL

In response to the Office action of April 2, 2003, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the list of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.